

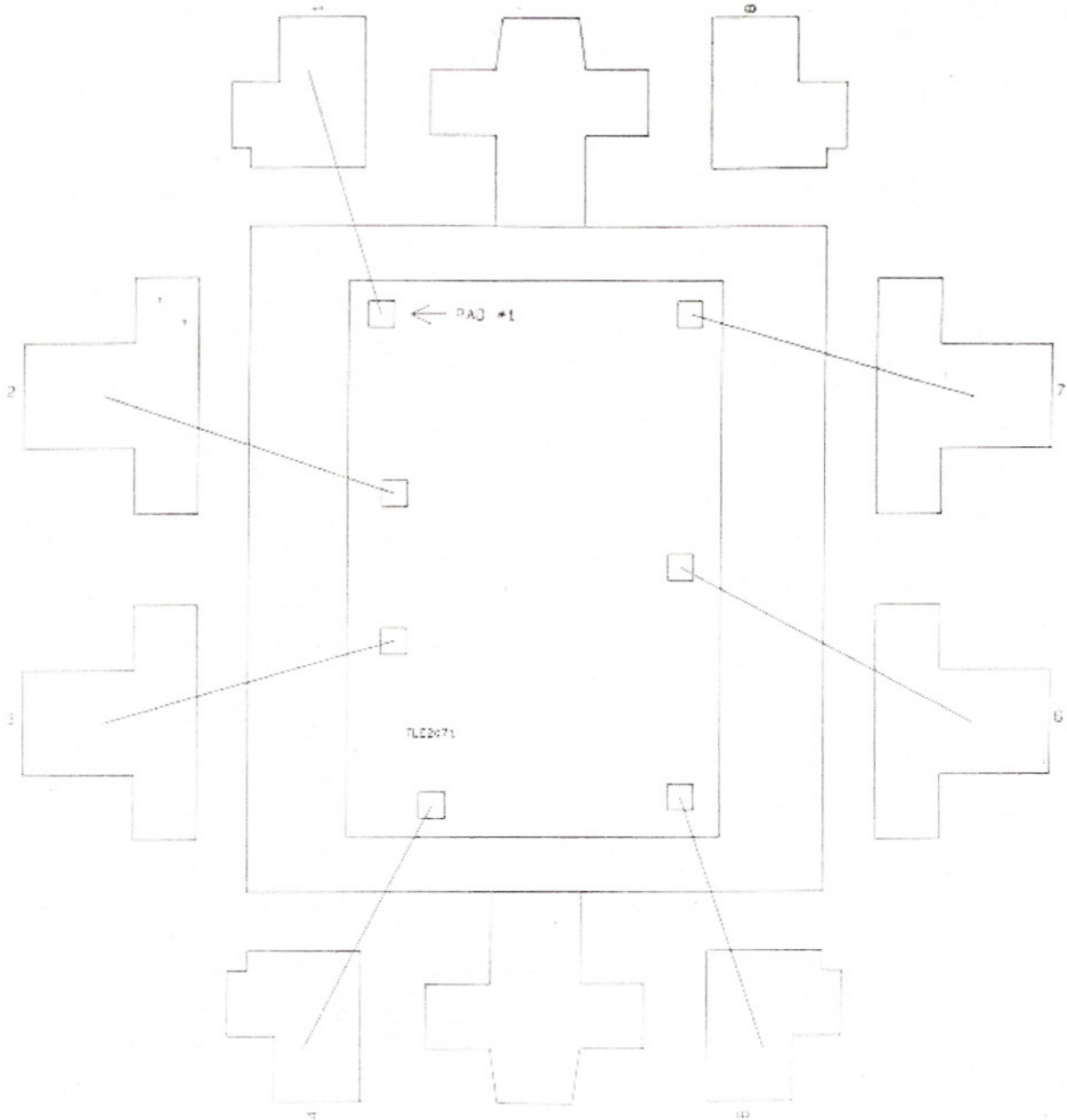


Sierra Components, Inc.

2222 Park Place, 3-E -Minden, NV 89423

Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Topside Metal: Backside Metal: Backside Potential: Mask Ref.: Bond Pads: 15 Mils

APPROVED BY: MG

DIE SIZE : 58 x 85 Mils

DATE: 6/24/05

MFG: Texas Instruments

THICKNESS:

P/N: TLE2071